3.3-V ABT OCTAL CLOCK DRIVER WITH 3-STATE OUTPUTS

SCAS500 - APRIL 1995

- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low-Static Power Dissipation
- 750-ps Maximum Output Skew Between All Outputs
- Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Bus-Hold Data Inputs Eliminate the Need for External Pullup Resistors
- Supports Live Insertion
- Packaged in Shrink Small-Outline Package (SSOP)

DB PACKAGE (TOP VIEW)						
		U		L		
10E [1		20	<u> </u>		
1A1 🏻	2		19] 20E		
2Y4 🛚	3		18] 1Y1		
1A2 🛚	4		17	2A4		
2Y3 🛚	5		16	1Y2		
1A3 🛛	6		15	2A3		
2Y2 🛚	7		14	1Y3		
1A4 🛚	8		13	2A2		
2Y1 🛛	9		12] 1Y4		
GND [10)	11	2A1		

description

The CDC3244 is designed specifically for low-voltage 3.3-V $V_{\rm CC}$ operation, but with the capability to provide a TTL interface to a 5-V system environment. The CDC3244 provides a low-cost solution in applications that require skews of less than 750 ps.

The CDC3244 is organized as two 4-bit line drivers with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the device passes data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.

Active bus-hold circuitry holds unused or floating data inputs at a valid logic level.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to VCC through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The CDC3244 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

FUNCTION TABLE (each driver)

INP	UTS	OUTPUT
ŌĒ	Α	Υ
L	Н	Н
L	L	L
Н	X	Z



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logic symbol[†]

2A1

2A2

2A3

2A4

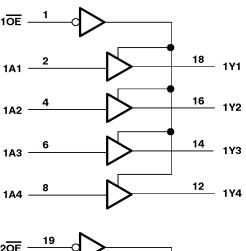
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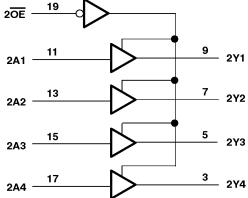
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17

10E ΕN 18 ∇ 1A1 1Y1 16 1A2 1Y2 14 1A3 1Y3 8 12 1A4 **1Y4** 2OE ΕN 11 D ∇

logic diagram (positive logic)





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

2Y1

2Y2

2Y3

2Y4

7

5

3

Supply voltage range, V _{CC}	-0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)	-0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, VO (see Note 1)	-0.5 V to 7 V
Current into any output in the low state, IO	128 mA
Current into any output in the high state, IO (see Note 2)	64 mA
Input clamp current, I _{IK} (V _I < 0)	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Maximum power dissipation at T _A = 55°C (in still air) (see Note 3)	0.6 W
Storage temperature range, T _{stq} –	·65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
 - 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the Package Thermal Considerations application note in the 1994 ABT Advanced BiCMOS Technology Data Book, literature number SCBD002B.



[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
fclock	Clock frequency				MHz
Vcc	Supply voltage		2.7	3.6	V
V_{IH}	High-level input voltage		2		٧
V _{IL}	Low-level input voltage			0.8	V
VI	Input voltage			5.5	٧
ЮН	High-level output current			-32	mA
loL	Low-level output current			64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10	ns/V
TA	Operating free-air temperature		-40	85	°C

NOTE 4: Unused or floating control inputs must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
VIK	$V_{CC} = 2.7 V,$	I _I = -18 mA				-1.2	V
	V _{CC} = MIN to MAX [‡] ,	I _{OH} = -100 μA			.2		
Voн	$V_{CC} = 2.7 \text{ V},$	I _{OH} = – 8 mA		2.4			V
	V _{CC} = 3 V,	I _{OH} = -32 mA		2			
	V _{CC} = 2.7 V	I _{OL} = 100 μA				0.2	
	VCC = 2.7 V	I _{OL} = 24 mA				0.5	
VoL		I _{OL} = 16 mA				0.4) v
	V _{CC} = 3 V	I _{OL} = 32 mA				0.5	
		I _{OL} = 64 mA				0.55	
	V _{CC} = 0 or MAX [‡] ,	V _I = 5.5 V				10	
1,	V _{CC} = 3.6 V	V _I = V _{CC} or GND	Control pins			±1	μΑ
l II		V _I = V _{CC}	Data pins			1	
		V _I = 0	Data pins			-5	
l _{off}	V _{CC} = 0,	$V_{ }$ or $V_{ }$ = 0 to 4.5 V				± 100	μΑ
1175 - 1-15	V _{CC} = 3 V	V _I = 0.8 V	A inputs	75			μΑ
l(hold)	VCC - 0 V	V _I = 2 V	Amputa	-75			μΑ
^I OZH	V _{CC} = 3.6 V,	V _O = 3 V				5	μΑ
lozL	V _{CC} = 3.6 V,	V _O = 0.5 V				-5	μΑ
	, , , , , , , , , , , , , , , , , , ,	L 0	Outputs high		0.12	0.19	
	V _{CC} = 3.6 V, V _I = V _{CC} or GND	$I_{O}=0,$	Outputs low		8.6	12	mA
	V	Outputs disable			0.12	0.19	
Δl _{CC} §	V _{CC} = 3 V to 3.6 V, Other inputs at V _{CC} or GND	One input at V _{CC} – 0.6 V,				0.2	mA
Ci	V _I = 3 V or 0				4		pF
Co	V _O = 3 V or 0				8		pF

 $[\]dagger$ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.



For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

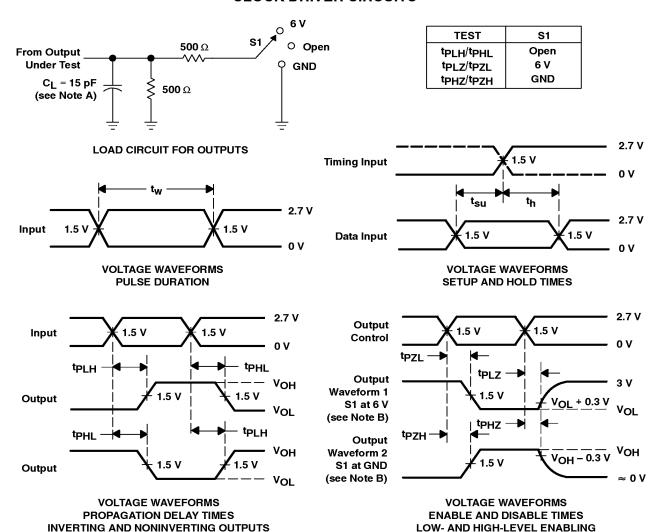
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switching characteristics over recommended operating free-air temperature range, C_L = 15 pF (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 3.3 V ± 0.3 V			V _{CC} = 2.7 V		UNIT
			MIN	TYP†	MAX	MIN	MAX	
tPLH	^	v	1	2.5	4.1		5	ne
t _{PHL}	A	'	1	2.5	4.1		5.2	ns
^t PZH	ŌĒ	V	1	2.7	5.2		6.3	ns
t _{PZL}	OE	1	1.1	3.1	5.2		6.7	115
^t PHZ	ŌĒ	>	1.9	3.9	5.6		6.3	ne
tPLZ		1	1.8	3.2	5.1		5.6	ns
t _{sk(o)}	А	Y			750		750	ps

 $^{^{\}dagger}$ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

PARAMETER MEASUREMENT INFORMATION CLOCK DRIVER CIRCUITS



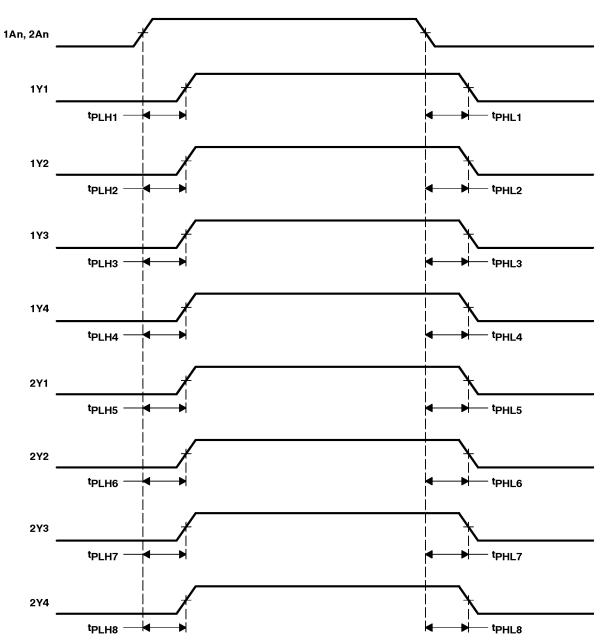
NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION



NOTE A: Output skew, $t_{sk(0)}$, is calculated as the greater of:

The difference between the fastest and slowest of tpLHn (n = 1, 2, ..., 8)

The difference between the fastest and slowest of t_{PHLn} (n = 1, 2, . . . , 8)

Figure 2. Waveforms for Calculation of $t_{sk(o)}$

